Product & Service Specifications

Flexible Circuitry: Multilayer Rigid-flex, Single & Double-Sided

Rigid Printed Wiring Boards: Multilayer, Single & Double-Sided

Materials: (RoHs Compliant)
* High Performance Flexible materials from *DuPont* (AP, FR, and LF).
* High Performance Laminates from *Isola, Nelco, Arlon, Rogers, Gore, Taconic, and Ventec.*
* Including Polyimide, FR4, Teflon, FR-27, FEP, and Ceramic filled composites.

Mechanical:
* Panel Size: 18" x 24" max; 12" x 18" min
* Layer Count: 24 max
* Hole Diameter: .004 drilled
* Line Width & Spacing: .003 min
* Dielectric Thickness Minimums: .001 Kapton, .002 (FR-4)
* Board Thickness: .125 max
* Aspect Ratio: 10:1
* Soldermask Clearance: .003 min, (1:1 With LDI Mask for Mask Defined BGA's)
* UL approved unpierced Area: 4"

Finishes:
* Electroless Nickel Immersion Gold (ENIG)
* Electroless Nickel Electroless Palladium Immersion Gold (ENEPIG)
* Hot-Air Solder Leveled
* Immersion Silver
* Electrolytic Wire Bondable Gold
* Electrolytic Hard Gold

Coatings:
* LPI Soldermask, Green, Blue, Red, Black, White
* LDI Soldermask, Green Satin, Red Satin, Blue Satin
* Flexible LDI Mask, Amber
* Silk screen: InkJet White, LPI Red, LPI Black, LPI Yellow

Special Processes:
* Controlled Impedance
* Bare Back Flex (Dual Access)
* Blind & Buried Via's
* Stacked Via's
* Back Drilling
* Via Plugging: Conductive & Non-Conductive
* Controlled Depth Milling
* Edge Plating & Exposed Edge Plated Holes
* Discreet Gold Plating